

MODEL  
**VTM-150M**  
**VTM-200M**  
 Semi-automatic DFR (Film Resist) Laminating Machine

*New*

**Outline**

These machines are the ideal manual system for laminating wafer and film under various conditions.  
 (With heater)

**Features**

- Applicable to tenting lamination, embedding lamination, ultra-thick resist lamination, conformal lamination and gas hermetic lamination etc. to wafer rough surface.
- For best lamination condition, applicable to setting laminating roller speed, roller table temperature and laminating vacuum pressure.



Specification	VTM-150M	VTM-200M
Wafer Size	4, 5, 6 inch wafer (Thickness spec needs separate consultation.)	6, 8 inch wafer (Thickness : 400~725 $\mu$ m)
Laminating film size	230mm ( 6inch )	290mm ( 8inch )
Utilities	Power	AC200V 3 phase 3 KVA / 5A
	Vacuum source	Pressure 0.5Mpa ( 40NI/min )
	N <sub>2</sub> source	Pressure 0.5Mpa
Dimensions	D 750 × W 1,300 × H 1,750 mm ( not including signal tower )	D 950 × W 1,600 × H 1,800 mm ( not including signal tower )
Weight	Approx. 550 kg	Approx. 700 kg

System appearance and specifications are subject to change without prior notice from the supplier.

313-1 Shindo-cho, Kashihara City, Nara, Japan 634-8580  
 Phone: +81 (0)744-24-7670  
 Fax: +81 (0)744-24-8352

URL <http://www.takatori-g.co.jp> E-mail [info@takatori-g.co.jp](mailto:info@takatori-g.co.jp)